

## Claims

1 (currently amended): A low application temperature hot melt adhesive ~~that is applied at temperature of below 250°F, has~~ having a viscosity between about 800 cps and 1500 cps at ~~the~~ an adhesive application temperature below 250°F, and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less.

2 (previously presented): The adhesive of claim 1 that is applied at a temperature of about 200°F.

3 (previously presented): The adhesive of claim 1 that is applied at or below a temperature of 200°F.

4 (previously presented): The adhesive of claim 1 wherein crystallization of the adhesive when analyzed by differential scanning calorimeter from application temperature to room temperature at a cooling rate of 150°C/min yields a time between initial cooling and crystallization of 0.35 minutes or greater.

5 (original): The adhesive of claim 1 that is thermally stable at application temperature for a period of one hundred hours as indicated by a viscosity change within plus/minus ten percent of the original application viscosity.

6 (original): The adhesive of claim 1 further comprising an energy absorbing ingredient.

7 (original): The adhesive of claim 1 further comprising a fragrance.

8 (original): An article of manufacture comprising the adhesive of claim 1.

9 (canceled)

10 (original): The article of claim 8 which is a carton, case, tray, bag or book.

11 (canceled)

12 (original): A packaged article contained within a carton, case, tray or bag, wherein the carton, case, tray or bag comprises the adhesive of claim 1.

13 (original): The packaged article of claim 12 which is a packaged food article.

14-21 canceled

22 (previously presented): The adhesive of claim 3 wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 90°F or less.

23 canceled.

24 canceled.

25 (previously presented): The adhesive of claim 1 comprising an ethylene n-butyl acrylate copolymer.

26 (currently amended): A low application temperature hot melt adhesive ~~that is applied at temperature of below 250°F~~, has having a viscosity between about 800 cps and 1500 cps at the an adhesive application temperature below 250°F, the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less, the crystallization of the adhesive when analyzed by differential scanning calorimeter from application temperature to

room temperature at a cooling rate of 150°C/min yields a time between initial cooling and crystallization of 0.35 minutes or greater, and is thermally stable at the application temperature for a period of one hundred hours as indicated by a viscosity change within plus/minus ten percent of the original application viscosity.

27 (previously presented): The adhesive of claim 1 which comprises 20 wt % of an ethylene n-butyl acrylate copolymer and 10 wt % of an ethylene vinyl acetate copolymer.

28 (previously presented): The adhesive of claim 26 that is applied at a temperature of about 200°F.

29 (previously presented): The adhesive of claim 26 that is applied at or below a temperature of 200°F.